

a layer of adhesive adhering the glass sheet to the semiconductor wafer, wherein the holes in the glass sheet are over the bond pads on the surface of the semiconductor wafer;

metallized pads formed on the glass sheet adjacent to each hole in the glass sheet; and

a conductive trace connecting each of the metallized pads to a corresponding bond pad on the surface of the semiconductor wafer. - -

Please amend Claim 4 as follows:

4. (Once amended) The chip scale structure of Claim [3]15 further comprising a solder ball formed on each metallized pad on the glass sheet.

Please add Claim 16 as follows:

- - 16. (New) The chip scale structure of Claim 15 wherein the holes in the glass sheet are tapered. - -

Please cancel Claim 5 and substitute new Claim 17 therefor as follows:

- - 17. (New) A chip scale structure comprising:

a semiconductor wafer with a pattern of bond pads on a surface of the semiconductor wafer, wherein the bond pads can be formed anywhere on the surface of the semiconductor wafer;

a glass sheet with holes in a pattern matching the pattern of bond pads on the surface of the semiconductor wafer;

a layer of adhesive adhering the glass sheet to the semiconductor wafer, wherein the holes in the glass sheet are over the bond pads on the surface of the semiconductor wafer; and

metallized pads formed on the glass sheet adjacent to each hole in the glass sheet, wherein the metallized pad extends down a portion of a side of the hole in the glass sheet. - -

Please amend Claim 6 as follows:

6. (Once amended) The chip scale structure of Claim [5]17 further comprising a metal plug formed in each hole connecting the metallized pad extending down a portion of a side of the hole in the glass sheet to the bond pad under the hole in the glass sheet.